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## In the Claims:

- (Currently amended) A semiconductor light emitting device 1. a II-VI group compound semiconductor formed on a 2 compound semiconductor substrate and comprising an active layer between an n-type cladding layer and a p-type cladding layer, further comprising an : type semiconductor 5 a first barrier layer consisting of a single monolayer of 6 Zn<sub>1-x-v</sub>Mq<sub>x</sub>Be<sub>v</sub>Se semiconductor material i-type an (0 < x + y < 1, 0 < x, 0 < y) having a band gap larger than 8 a band gap of said p-type cladding layer, provided between 9 and respectively directly in contact with said active layer 10 and said p-type cladding [[layer.]] layer, wherein said 11 active layer has a stacked structure including a quantum 12 well layer and a second barrier layer, and wherein said 13 n-type cladding layer is formed of  $Zn_1, Mq_2S_2Se_1-$  (0 < x < 1, 14 0 < y < 1). 15
  - 2. (Withdrawn Currently amended) The semiconductor light emitting device according to claim 1, wherein
- said light emitting device of the II-VI group compound is a ZnSe based light emitting device; and
- said n-type cladding layer is an n type  $Zn_{1-x}Mg_xS_ySe_{1-y}$ (0 < x < 1, 0 < y < 1) layer; and
- said p-type cladding layer is a p-type  $Zn_{1-x}Mg_xS_ySe_{1-y}$ 8 (0 < x < 1, 0 < y < 1) layer.

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- 3. (Currently amended) The semiconductor light emitting device
  2 according to claim 1, wherein a magnitude of the band gap
  3 of said <u>first</u> barrier layer is larger by 0.025 eV to 0.5 eV
  4 than the band gap of said p-type cladding layer.
- (Currently amended) The semiconductor light emitting device according to claim 1, wherein in the band gap of said <u>first</u> barrier layer, <u>an</u> energy of <u>a</u> valence band is approximately the same as or higher than that of said p-type cladding layer, and <u>an</u> energy of <u>a</u> conductive band is larger than that of said p-type cladding layer.

## Claims 5 to 11 (Canceled).

- 1 12. (Currently amended) The semiconductor light emitting device
  2 according to claim 1, wherein a thickness of said first
  3 barrier layer is at least 5 nm and at most equal to a
  4 thickness of said active layer.
- 1 13. (Original) The semiconductor light emitting device
  2 according to claim 1, wherein an n-type ZnSe single crystal
  3 substrate is used as said compound semiconductor substrate.
- 1 14. (Withdrawn) The semiconductor light emitting device
  2 according to claim 1, wherein an n-type GaAs single crystal
  3 substrate is used as said compound semiconductor substrate.

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1 15. (Withdrawn - Currently amended) The semiconductor light
emitting device according to claim 1, wherein in a stacked
structure including said compound semiconductor substrate
constituting said light emitting device which is a ZnSe
based light emitting device, a deviation between a peak of
X-ray diffraction of a plane orientation used as an index
of distortion from said substrate and a peak of X-ray
diffraction of said plane orientation from said stacked
structure is at most 1000 seconds.

Claims 16 to 27 (Canceled).

- 1 28. (New) The semiconductor light emitting device according to claim 1, wherein said p-type cladding layer is formed of ZnCdS.
- 29. (New) The semiconductor light emitting device according to claim 1, wherein said p-type cladding layer is formed of ZnMgSSe.

[RESPONSE CONTINUES ON NEXT PAGE]